

| ABRACON, LLC ENGINEERING/PROCESS CHANGE NOTIFICATION FORM | | | | |
|---|-----------------------|--|------------------|----------------|
| ABRACON ENGINEERING ORIGINATOR: | | IMPLEMENTATION DATE: 03/18/2019 | | |
| Gurpreet Narula – Sr Product Engineer | | SCD/DRAWING AFFECTED: | | |
| NOTIFICATION DATE: | | ABM2 Series Ceramic Surface Mount Microprocessor Crystal | | |
| 03/18/2019 | | REV: Q | | |
| | | NEW REV: P | | |
| | | EFFECTIVITY DATE: <u>03/18/2019</u> | | |
| | | ECO# 3431 | | |
| REASON FOR CHANGE: | | | | |
| To align with the production packaging. DETAILS OF SPECIFICATION CHANGE: | | APPLICATION INFORMATION | | |
| Increased the tolerance for the height specification. | | Safety | Non Safety | Application: |
| | | | | 7 . p p |
| Original device dimensions & associated tolerance: Length= (8.00±0.15) mm Width= (4.50±0.15) mm Height= (1.40±0.20) mm | | (Check one) | | |
| Height= (1.40± <mark>0.20</mark>) min | | | | |
| Revised device dimensions & | associated tolerance: | | | |
| Length= (8.00±0.15) mm Width= (4.50±0.15) mm | | | 0 | |
| Height= (1.40± <mark>0.50</mark>) mm | | | | |
| | | | ON OFCURRENT | STOCK |
| | | ☐ Scrap ☐ Transfer to: | | |
| | | √ Use as is | | |
| | | ☐ Return to vendor | | |
| ABRACON INTERNAL APPROVAL APPROVAL (PRES) <u>Mike Calabria</u> DATE | | | <u>3/18/2019</u> | |
| GLOBAL QUOTING/PRICING MGR _Hector Lopez | | DATE 0 | <u>3/18/2019</u> | |
| ENGINEERING VP | Syed Raza | DATE 03/18/2019 | | |
| PURCHASING MGR | Ying Huang | DATE 03/18/2019 | | |
| SALES VP | Mike White | DATE <u>03/18/2019</u> | | |
| QUALITY & PROCEESS IMPROVEMENT MGR: Reuben Quintanilla DATE 03/18/2019 | | | | |
| CUSTOMER APPROVAL (If Applicable) | | | | |
| ENGINEERING: NAME:TITLE: | | | | DATE: |
| BLIVER/DLIPCHASING: NAME: | | 1 E· | | DATE: |